Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Previously Presented) A cover tape for tape-packaging electronic components, for heat-sealing a carrier tape storing therein electronic components, comprising:

a substrate film layer;

a soft material layer; and

a thermal adhesive layer; wherein

the soft material layer is formed of metallocene linear low-density polyethylene; and

the metallocene linear low-density polyethylene has a specific gravity in a range of from 0.888 to 0.907,

wherein a softening temperature of the metallocene linear low-density polyethylene measured by a TMA method defined in JIS K7196 is in a range of from 75°C to 97°C.

2. (Original) The cover tape for tape-packaging electronic components according to claim 1, wherein

the metallocene linear low-density polyethylene has a specific gravity in a range of from 0.892 to 0.907.

3. (Canceled)

4. (Canceled)

5. (Canceled)

6. (Previously Presented) The cover tape for tape-packaging electronic components according to claim 2, wherein

in a case where the thermal adhesive layer heat-seals the carrier tape, the thermal adhesive layer and the soft material layer are separated from each other in the heat-sealed area

upon a peeling operation of the cover tape for tape-packaging electronic components from the carrier tape;

a peeling strength upon separation of the soft material layer from the thermal adhesive layer is in a range of from 0.1 N/mm width to 1.3 N/mm width, and

a difference between a maximum value of the peeling strength upon separation of the soft material layer from the thermal adhesive layer and a minimum value thereof is equal to or less than 0.3 N/mm width.

7. (Canceled)

8. (Previously Presented) The cover tape for tape-packaging electronic components according to claim 1, wherein

in a case where the thermal adhesive layer heat-seals the carrier tape, the thermal adhesive layer and the soft material layer are separated from each other in the heat-sealed area upon a peeling operation of the cover tape for tape-packaging electronic components from the carrier tape;

a peeling strength upon separation of the soft material layer from the thermal adhesive layer is in a range of from 0.1 N/mm width to 1.3 N/mm width, and

a difference between a maximum value of the peeling strength upon separation of the soft material layer from the thermal adhesive layer and a minimum value thereof is equal to or less than 0.3 N/mm width.

9. (Previously Presented) The cover tape for tape-packaging electronic components according to claim 1, wherein a melting point of the metallocene linear low-density polyethylene measured by a DSC method defined in JIS K7121 ranges from 60°C to 87°C.

10. (New) The cover tape for tape-packing electronic components according to claim 1, wherein the cover tape has a total light transmissivity that is equal to or more than 50%.

11. (New) The cover tape for tape-packing electronic components according to claim 1, wherein the cover tape has a total light transmissivity that is equal to or more than 75%.

12. (New) The cover tape for tape-packing electronic components according to claim 1, wherein the cover tape has a haze that is equal to or less than 50%.